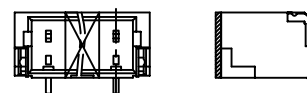
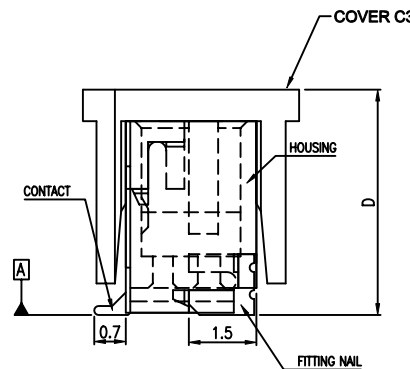
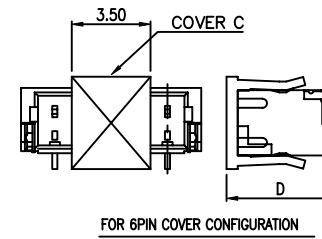
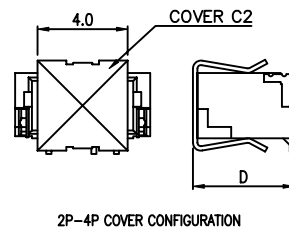
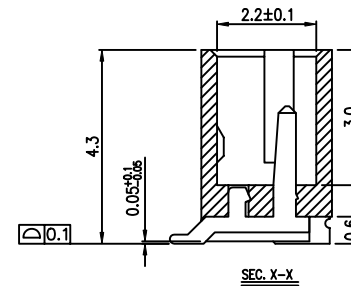


PCB PATTERN LAYOUT



WITH MYLAR CONFIGURATION



- NOTES:
1. MATERIAL:
 - 1.1 HOUSING: NYLON UL94V-0
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 - 1.4 COVER TYPES:
 - COVER-C2 :STAINLESS STEEL
 - COVER-C3 :NYLON UL94V-0
 - COVER-C : NYLON UL94V-0
 2. FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: MATTE TIN 100u" MIN. OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - MATTE TIN PLATING 100u" MIN. OVERALL
 3. REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
 4. SPEC. PLS. REFER TO GS-12-572.
 5. PACKAGE PLS. REFER TO GS-14-1314.
 6. PART NUMBER DESCRIPTION:

10089715-XXX 0 0 LF

 - NO OF CONTACTS
 - PACKING
 - 0: TAPE REEL
 - PLATING
 - 0: MATTE TIN
 - LEAD FREE
 - COLOR
 - 0: NATURAL

CKT	Dim.A	Dim.B	Dim.C	Dim.D
004	3.0	4.4	6.0	4.5
005	4.0	5.4	7.0	5.0
006	5.0	6.4	8.0	4.8
007	6.0	7.4	9.0	5.0
008	7.0	8.4	10.0	5.0
010	9.0	10.4	12.0	5.0
012	11.0	12.4	14.0	5.0

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.X ± 0.25	projection		www.fciconnect.com	
E	T09-1108	WL	08/19/09		.XX ± 0.15			title 1.0mm WIRE TO BOARD CONN. WAFER SMT S/T TYPE	
F	T09-1151	WL	11/25/09		.XXX ± 0.10				
G	T10-0004	WL	01/05/10	angles	0° ± 2°			product family WIRE TO BOARD	
H	T10-0064	WL	05/17/10	dr	LEIF SHEN	06/18/08			
				enr	LEIF SHEN	06/18/08		size dwg no	
				chr	LEIF SHEN	06/18/08			
				appd	JOSEPH HSIA	06/18/08		A4 10089715	
sheet index	revision sheet	H	1						
								code	
								22526	
								Printed: Jun 21, 2010	